

## PRELIMINARY SPECIFICATION



Part No.: **TDRF750B100**

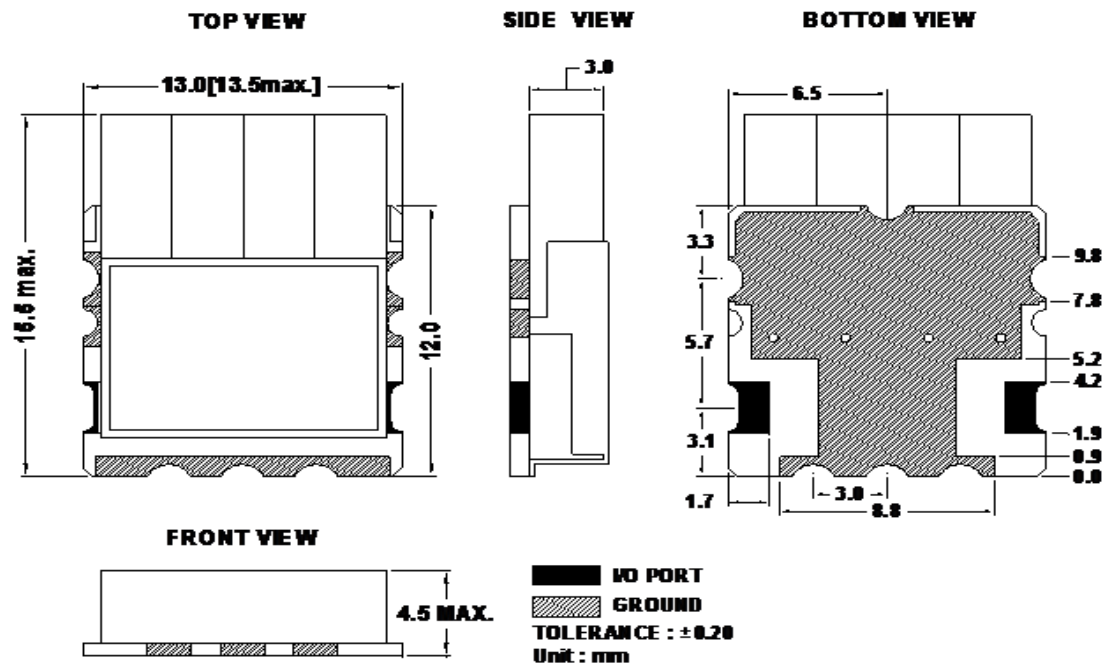
Customer:

Date: **2015-07-28**

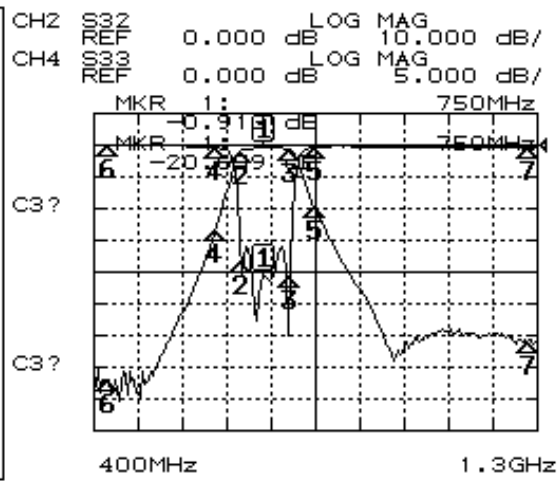
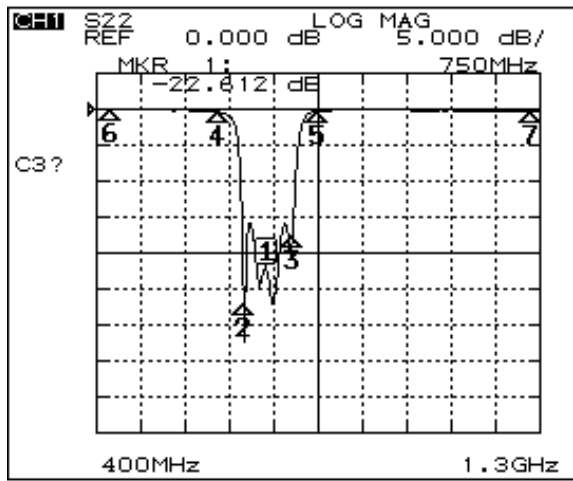
Written by	Checked by	Approval

ELECTRICAL SPECIFICATIONS		
ITEM	SPEC	UNIT
1	Center Frequency [fo]	750.0
2	Bandwidth [BW]	Fo ±50 [700.0~800.0]
3	Insertion Loss in Fo	2.0
4	Ripple in BW	1.0
5	Return Loss in BW	
6	Attenuation [Absolute Value]	18 dB min @ fo ±100 [ 650 & 850 ] 70 dB min @ fo -320 [ 430 & ] 60 dB min @ fo +535 [ & 1285.0 ]
7	Input Power	3.0
8	In/Out Impedance	50
9	Operation Temperature Range	-40 ~ +85

### DIMENSIONS



### PERFORMANCE



CH2 MARKER LIST			
1	750.000000	MHz	-0.9113
2	700.000000	MHz	-1.0014
3	800.000000	MHz	-1.0014
4	400.000000	MHz	-2.0610
5	1.400000	GHz	-1.9410
6	1.280000	GHz	-7.4213
7	1.300000	GHz	-6.2123

CH4 MARKER LIST			
1	750.000000	MHz	-2.0064
2	700.000000	MHz	-1.0064
3	800.000000	MHz	-1.0064
4	400.000000	MHz	-1.0064
5	1.400000	GHz	-0.4093

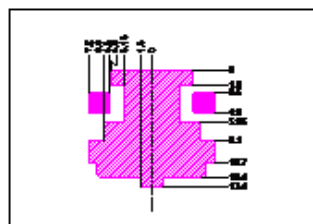
### RECOMMENDED PC BOARD PATTERN

**BOTTOM**



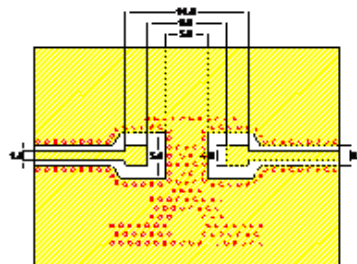
○ Through Hole

**SOLDER RESIST**



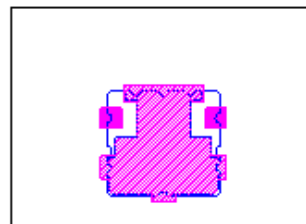
■ GROUND HOLDING POINT  
■ NO PWR HOLDING POINT

**FRONT**



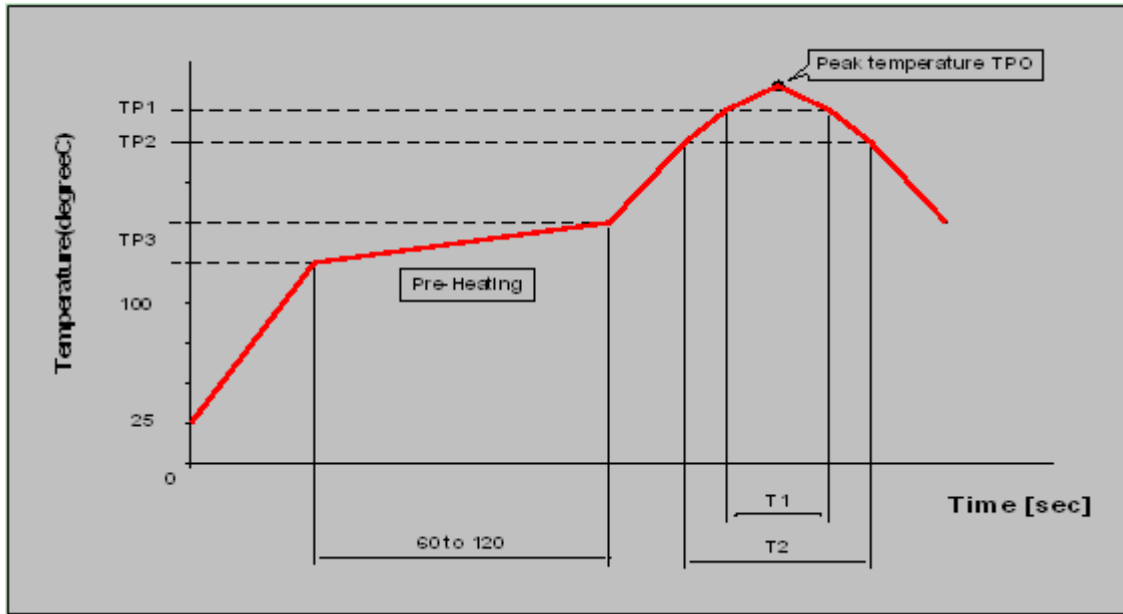
■ ELECTRODE

**FOOTPRINTS**



— PRODUCT

**SOLDERING CONDITION**



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 130
Test condition of reflow test resistance	260+5/-0	240	20	220	70	150 to 130